

Application Serial No. 10/800,603
Reply to Office Action of May 5, 2005

PATENT
Docket: CU-3637

REMARKS/ARGUMENTS

Reconsideration is respectfully requested.

Claims 1-18 are pending in the present application before this amendment. By the present amendment, Claim 7 and 13-18 have been amended. Claim 19 has been added. No new matter has been added.

In the Office Action, Claims 13-18 stand objected to for containing informalities.

Applicants respectfully submit that Claims 13-18 do **not** depend from Claim 1 and do **not** redundantly claim the subject matter set forth in Claim 1. That is, Claim 1 is directed to "a semiconductor substrate device," but Claim 13 is directed to "a semiconductor device" having the "semiconductor substrate device" having the limitations as recited in Claim 1 (this is not to be confused as if Claim 13 depends from Claim 1).

To make clear, Claim 13 has been amended to individually recite all limitations of Claim 1. Similar amendments have been made to Claims 14-18. Withdrawal of the objection is respectfully requested.

In the Office Action, Claims 1, 4-7, 12-13, and 16-18 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 6,737,742 (Sweterlitsch). Claims 2-3, 8-11, and 14-15 stand rejected under 35 U.S.C. § 103(a) as being obvious Sweterlitschin view of U.S. Patent Application Publication No. 2002/0100611 (Crockett). The "et al." suffix, which may appear after a reference name, is omitted in this paper.

In the presently claimed invention, as clearly mentioned in Claim 1 and amended Claim 7 (as well as Claims 13 and 19), the reinforcing member 27A is provided in the substrate body 25. More specifically a part of the reinforcing member 27A is embedded

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in the substrate body 26, as discussed at Specification page 12, lines 14-16 and the new claim 19.

Since the reinforcing member is larger than the opening forming portion of the base and provided in the substrate body at a portion corresponding to the opening forming portion, it is possible to reinforce the substrate body at the portion corresponding to the opening forming portion (Specification page 15, line 15 to page 16, line 9).

On the other hand, Sweterlitsch's board 230 as allegedly corresponding to the claimed reinforcing member according to the Office Action is **NOT** provided in the base 100 allegedly corresponding to the substrate base in the cited Sweterlitsch reference. Rather, Sweterlitsch's board 230 is above the base 100. At least on this point, the presently claimed invention is quite different from Sweterlitsch.

Accordingly, the independent Claims 1, 7, 13 and 19 are not taught or suggested by Sweterlitsch, either individually or in combination with any of the cited references.

For the reasons set forth above, Applicants respectfully submit that Claims 1-19, now pending in this application, are in condition for allowance over the cited references. This amendment is considered to be responsive to all points raised in the Office Action. Accordingly, Applicants respectfully request reconsideration and withdrawal of the outstanding rejections and earnestly solicit an indication of allowable subject matter.


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Should the Examiner have any remaining questions or concerns, the Examiner is encouraged to contact the undersigned attorney by telephone to expeditiously resolve such concerns.

Respectfully submitted,

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